

DIALOG(R)File 351:Derwent WPI
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**Storage-stable adhesive for printed circuit board - comprises
polyacrylonitrile-polybutadiene rubber, alkylphenol resin, polyepoxy
resin and crosslinking agent**

Patent Assignee: HITACHI CHEM CO LTD (HITB)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 3255185	A	19911114	JP 9053044	A	19900305	199201 B

Priority Applications (No Type Date): JP 9053044 A 19900305

Abstract (Basic): JP 3255185 A

The adhesive for a printed circuit board made by electroless plating of a circuit pattern comprises (A) acrylonitrile-butadiene rubber including glycidyl methacrylate, (B) alkylphenol resin, (C) epoxy resin and (D) a crosslinking agent for glycidyl methacrylate and the epoxy resin.

Pref. the compsn. comprises, as solid excluding solvent, 30-70 wt.% of (A), 10-40 wt.% of (B), 5-50 wt.% of (C) and 0.01-5 wt.% of (D). The crosslinking agent (D) is an amine complex cpd. of boron trifluoride.

USE/ADVANTAGE - The adhesive exhibits improved anti-galvanic corrosion and storage stability. (6pp Dwg.No.0/0)

Title Terms: STORAGE; STABILISED; ADHESIVE; PRINT; CIRCUIT; BOARD; COMPRISE
; POLYACRYLONITRILE; POLYBUTADIENE; RUBBER; ALKYLPHENOL; RESIN;
POLYEPoxide; RESIN; CROSSLINK; AGENT

Index Terms/Additional Words: PCB; POLYPHENOL

Derwent Class: A18; A21; A81; G03; L03; V04

International Patent Class (Additional): C08L-061/06; C08L-063/00;
C09J-109/02; C09J-161/06; C09J-163/00; H05K-003/18

File Segment: CPI; EPI